

## **AMENDMENTS TO THE SPECIFICATION:**

Please replace the paragraph beginning at page 1, line 19, with the following rewritten paragraph:

1       As an example, an integrated circuit ~~a specific ASP-Wireless device~~  
2       containing an Analog to Digital Converter (ADC) typically requires test  
3       verification. The test verification of two key parameters F(full scale)set and  
4       Z(zero)set is usually considered ~~are critical in such cases~~. Unfortunately, contact  
5       resistance during bump probing is often too high to correctly validate the  
6       operation of the ADC for these two parameters.

## **IN THE ABSTRACT:**

Please replace the paragraph beginning at page 19, line 4, with the following rewritten paragraph:

1       Apparatus and methods for testing conductive bumps or target test points  
2       on integrated circuits, ~~comprising~~ A a multiplicity of probes are extended  
3       extending through a support substrate. At least one of the multiplicity of probe  
4       locations include ~~including~~ a second electrically isolated probe such that the test  
5       point is in contact with two probes. One of the two probes provides ~~providing~~ a  
6       voltage to the test point and the second probe sensing the voltage so as to  
7       provide a Kelvin connection.